



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Nov 05, 2014 08:49 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
BAS16HT1G	BAS16HT1G	SOD-323F-2 (Eutectic_G).csv			Subcon	0.004977	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration * 1 - Item(s) does not contain RoHS restricted substances per the definition above		Supplier Acceptance * Accepted
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
<div style="margin-bottom: 10px;">Exemption List Version EL-2011/534/EU</div> <div style="margin-bottom: 10px;">none</div>		

Declaration Signature	
<div style="border: 1px solid black; height: 40px; margin-bottom: 5px;"></div> Supplier Signature	<div style="text-align: center; margin-bottom: 10px;">  </div> <div style="text-align: center;"> DAVID LANCASTER - PRODUCT ECOLOGY MANAGER </div>

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOD-323F-2 (Eutectic_G).csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Lead Frame	Copper Alloy	1.124	Supplier	-	Iron	0.001	7439-89-6	201
			Supplier	-	Copper	1.123	7440-50-8	225638
			Supplier	-	Phosphorus	0.0003	7723-14-0	60
Plating	Solder	0.185	Supplier	-	Tin	0.185	7440-31-5	37171
Chip	Other inorganic materials	0.073	Supplier	-	Silicon	0.067	7440-21-3	13462
			Supplier	-	Gold	0.006	7440-57-5	1206
			Supplier	-	Aluminum	0.0001	7429-90-5	20
Encapsulation	Thermoplastics	3.586	Supplier	-	Silica, vitreous	2.547	60676-86-0	511754
			Supplier	-	Epoxy Resin	0.86	29690-82-2	172795
			Supplier	-	Carbon Black	0.018	1333-86-4	3617
			Supplier	-	Phenolic resin (in MC)	0.161	9003-35-4	32349
Wire Bond - Au	Gold & its alloys	0.009	Supplier	-	Gold	0.009	7440-57-5	1808